INCH-POUND

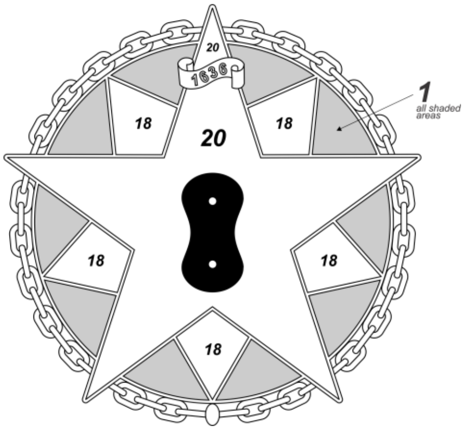
MIL-DTL-3628/276
3 January 2018

DETAIL SPECIFICATION SHEET

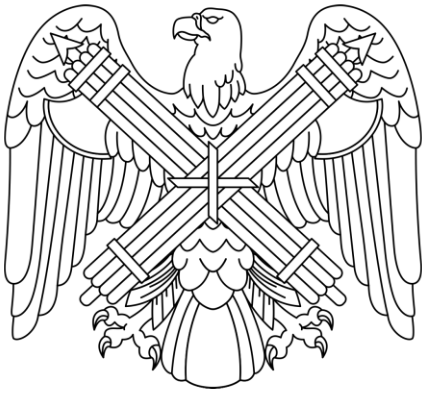
BADGE, IDENTIFICATION, NATIONAL GUARD BUREAU

This specification is approved for use by all
Departments and Agencies of the Department of Defense

The requirements for acquiring the product described herein shall consist of this specification sheet and MIL-DTL-3628.



BASE



DEVICE

ASSEMBLED

DASH NO.
-1: Regular size
-2: Miniature Size

MATERIAL: (-1 and -2) Red Brass 85/15 (UNS Alloy No.C-230)

AMSC N/A FSC 8455

FINISH:
BASE: Epoxy resin 24K Gold Plated Matte Finish, Polished Highlights and shall match The Institute of Heraldry (TIOH) Metal Finish Chip Number 8.
DEVICE: Epoxy resin 24K Gold Plated, Mirror- like Polish and shall match TIOH Metal Finish Chip Number 6.

DIMENSIONS:
- BASE DIAMETER:
  - -1: 2 inches (REF)
  - -2: 1-1/2 inches (REF)
- DEVICE:
  - HEIGHT:
    - -1: 1-1/8 inches (REF)
    - -2: 13/16 inch (REF)
  - WIDTH:
    - -1: 1-5/32 inches (REF)
    - -2: 7/8 inch (REF)
- THICKNESS BASE:
  - -1: 0.099 ± 0.010 inch
  - -2: 0.092 ± 0.010 inch
- THICKNESS DEVICE:
  - -1: 0.099 ± 0.010 inch
  - -2: 0.082 ± 0.010 inch
- THICKNESS OVERALL:
  - -1: 0.198 ± 0.010 inch
  - -2: 0.173 ± 0.010 inch

ATTACHING DEVICE:

1. The attaching device shall be three prongs and flat ball clutches.

2. Three prongs shall be located on the reverse on 1-3/4 inch diameter circle for -1. Three prongs shall be located on the reverse on 1-1/4 inch diameter circle for -2. The prongs shall be spaced 120 degrees apart with the bottom prong located on the vertical center line 1/8 inch from the bottom. Prongs for -1 shall be 7/16 inch long.

EPOXY:

1. Epoxy resin shall be applied to the Badge Qualification and shall match TIOH Hard Enamel Color Chip Numbers listed below.

TIOH HARD ENAMEL COLOR CHIPS	
COLOR	**CHIP NUMBER**
Blue	#18
Red	#1
Blue	#20

2. BASE: The large star shall be filled with Blue Epoxy #20. The background star shall be filled with Blue Epoxy #18 and the background filled with Red Epoxy #1. Epoxy shall be stoned.

3. DEVICE: Two posts shall be soldered on the back of the device on the vertical centerline a 1/2 inch apart for -1. Two posts shall be soldered on the back of the device on the vertical centerline a 1/4 inch apart for -2. The device will be swaged to the base. In addition to the swage, a glue or adhesive may be used to further strengthen the connection between the base and device.

NOTES:
1. The term (REF) refers to the measurements taken from the Government furnished hub or die.

2. Hard cloisonné enamel may be used in lieu of epoxy. If hard cloisonné enamel is used, the required base material shall be Gilding Metal 95/5 (UNS Alloy C-210).

Custodian: Army - IH	Preparing activity: Army - IH
Review activity: DLA - CT	(Project No. 8455-2018-082)

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at https://assist.dla.mil.